

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S16	1218	257/778.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:40
S17	192	257/685.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:40
S18	786	257/686.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:40
S19	706	257/787.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:40
S20	1029	257/737.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:41
S21	979	257/738.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:41
S22	462	257/723.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:44
S23	614	257/777.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:44
S24	25	257/731.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:48

S25	11	257/733.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:48
S26	98	257/730.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:49
S27	202	257/782.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:49
S28	377	257/783.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:49
S29	354	257/786.ccls. and (bump ball) with (adhesive encapsulat \$3 encapsulant mold\$3 seal\$3 sealant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:49
S31	44	Boon-Suan-Jeung.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/02 19:50
S32	16	("20020027257" "20020164840" "20040058472" "5102829" "5731227" "6150717" "6194250" "6204562" "6228687" "6236109" "6239367" "6268648" "6368896" "6765299" "6815254" "6847109").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 19:52
S33	272	257/E23.021	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 19:56
S34	152	257/E23.069	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 19:56

S35	132	257/E21.508	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 19:56
S36	108	257/E21.503	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:02
S37	103	257/E21.511	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:02
S38	108	257/E51.02	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:02
S40	100	257/E33.059	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:03
S41	38	257/E31.117	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:03
S42	72	257/E23.116	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:05
S43	171	257/E21.502	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/02 20:06

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